First Edition Sep 8, 2005

# **LCD Module Technical Specification**

Final Revision

## Type No. F-51553GNBJ-LW-AEN

m. Abatouted

Approved by (Quality Assurance Division)

S. Matsucker

Checked by (ACI Engineering Division)

TUUTO

Prepared by (ACI Engineering Division)

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## **Revision History**

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## 1.General Specifications

Operating Temp.	:	min20°C ~max	к. 70°С	
Storage Temp.	:	min30°C ~max	к. 85°С	
Dot Pixels	:	128 (W) × 64 (H	H) dots	
Dot Size	:	0.48 (W) × 0.48	3 (H) mm	
Dot Pitch	:	0.50 (W) × 0.50	) (H) mm	
Viewing Area	:	66.8 (W) × 35.5	5 (H) mm	
Outline Dimensions	:	89.7 (W) × 49.8 * Without FPCU	9* (H) × 6.0 (D) mm V	
Weight	:	33.0g max.		
LCD Type	:		de / Transmissive)	
Viewing Angle	:	6:00		
Data Transfer	:	8-bit parallel data Serial data trans		
Backlight	:	LED Backlight /	White	
Drawings	:	Dimensional Out	tline UE-311234B	
RoHS regulation	:	requirement of R Our company is	wledge, this product satisfies mat oHS regulation. doing the best efforts to obtain ertificate from our suppliers.	erial
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## 2.Electrical Specifications

2.1. Absolute Maximum Ratings

			G	ND=0V	
Parameter	Symbol	Conditions	Min.	Max.	Units
Supply Voltage	Vdd-GND	-	-0.3	7.0	V
(Logic)					
Supply Voltage	Vdd-GND	-	-6.0	+0.3	V
(Booster Circuit)					
Supply Voltage 1	V5,Vout	-	-18.0	+0.3	V
(LCD Drive)					
Input Voltage	Vin	-	-0.3	Vdd+0.3	V

2.2.DC Characteristics

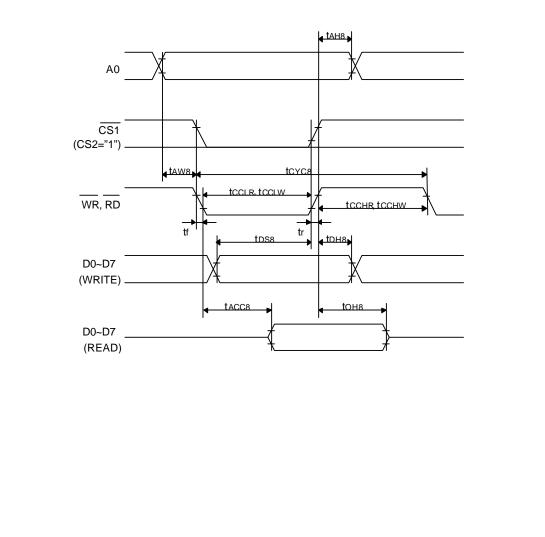
					Ta=25°C, G	ND=0V
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Supply Voltage	VDD-GND	With Triple	4.5	-	5.5	V
(Logic)		With Quad	2.7	-	3.3	
Supply Voltage (LCD Drive)	Vdd-V5		Shown in 3.	1		V
"High" Level Input Voltage	Vін	-	0.8×Vdd	-	Vdd	V
"Low" Level Input Voltage	Vil	-	GND	-	0.2×Vdd	V
"High" Level Output Voltage	Vон	lон=-0.1mA	0.8×Vdd	-	Vdd	V
"Low" Level Output Voltage	Vol	loL=0.1mA	GND	-	0.2×Vdd	V
Supply Current	lod	VDD-GND=5.0V	-	0.84	1.26	mA

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#### 2.3.AC Characteristics

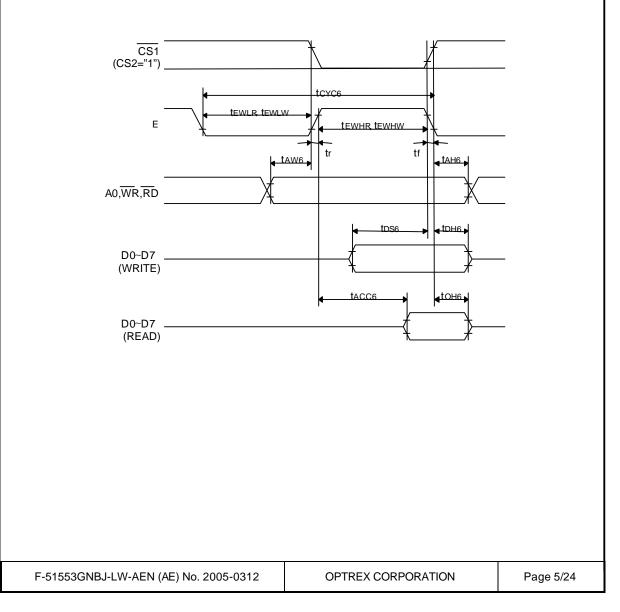
#### 2.3.1.Read/Write Operation Sequence (80 series CPU)

		•		Vdd	=5.0V±10%
Parameter		Symbol	Min.	Max.	Units
Address Setup Time		t <sub>AW8</sub>	0	-	ns
Address Hold Time		t <sub>AH8</sub>	0	-	ns
System Cycle Time		t <sub>CYC8</sub>	166	-	ns
Control Low Pulse Width	WRITE	<b>t</b> <sub>CCLW</sub>	30	-	ns
	READ	<b>t</b> <sub>CCLR</sub>	70	-	ns
Control High Pulse Width	WRITE	<b>t</b> <sub>сснw</sub>	30	-	ns
	READ	<b>t</b> <sub>CCHR</sub>	30	-	ns
Data Setup Time		t <sub>DS8</sub>	30	-	ns
Data Hold Time		t <sub>DH8</sub>	10	-	ns
RD Access Time		t <sub>ACC8</sub>	-	70	ns
Output Disable Time		t <sub>OH8</sub>	5	50	ns



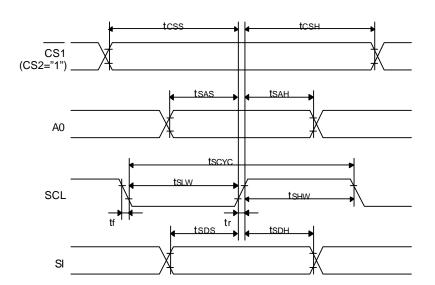
2.3.2. Read/Write O	peration Seq	uence (68	series CPU)
2.0.2.110000, 11110 0	poration bog		

	•			Vdd	=5.0V±10%
Parameter		Symbol	Min.	Max.	Units
Address Setup Time		t <sub>AH6</sub>	0	-	ns
Address Hold Time		t <sub>AW6</sub>	0	-	ns
System Cycle Time		<b>t</b> cyc6	166	-	ns
Data Setup Time		t <sub>DS6</sub>	30	-	ns
Data Hold Time		t <sub>DH6</sub>	10	-	ns
Access Time (CL=100pF)		t <sub>ACC6</sub>	-	70	ns
Output Disable Time		t₀ <sub>H6</sub>	10	50	ns
Enable High Pulse Width	READ	<b>t</b> ewhr	70	-	ns
	WRITE	<b>t</b> ewhw	30	-	ns
Enable Low Pulse Width	READ	<b>t</b> <sub>EWLR</sub>	30	-	ns
	WRITE	t <sub>ewlw</sub>	30	-	ns



### 2.3.3. Serial Interface Sequence

			Vc	o <b>⊳=5.0±10%</b>
Parameter	Symbol	Min.	Max.	Units
Serial Clock Cycle Time	t <sub>scyc</sub>	200	-	ns
Serial Clock High Pulse Width	t <sub>sнw</sub>	75	-	ns
Serial Clock Low Pulse Width	t <sub>sLW</sub>	75	-	ns
Address Setup Time	t <sub>sas</sub>	50	-	ns
Address Hold Time	t <sub>sah</sub>	100	-	ns
Data Setup Time	t <sub>sDS</sub>	50	-	ns
Data Hold Time	t <sub>sDH</sub>	50	-	ns
Chip Select Setup Time	tcss	100	-	ns
Chip Select Hold Time	t <sub>сsн</sub>	100	-	ns



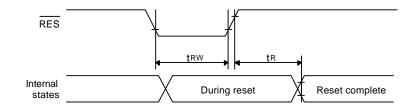
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#### 2.3.4. Display Control Timing Characteristics

Reset Input Timing VD					D=5.0±10%
Parameter	Symbol	Min.	Тур.	Max.	Units
Reset time	t <sub>R</sub>	-	-	0.5	
Reset "L" Pulse Width	<b>t</b> <sub>RW</sub>	0.5	-	-	μs

Output TimingVDD=5.0±10%							
Parameter	Symbol	Min.	Тур.	Max.	Units		
FR Delay Time	<b>t</b> <sub>DFR</sub>	-	10	40	ns		

Note 1 :Valid only when the master mode is selected. Note 2:All timing is based on 20% and 80% of Vss.

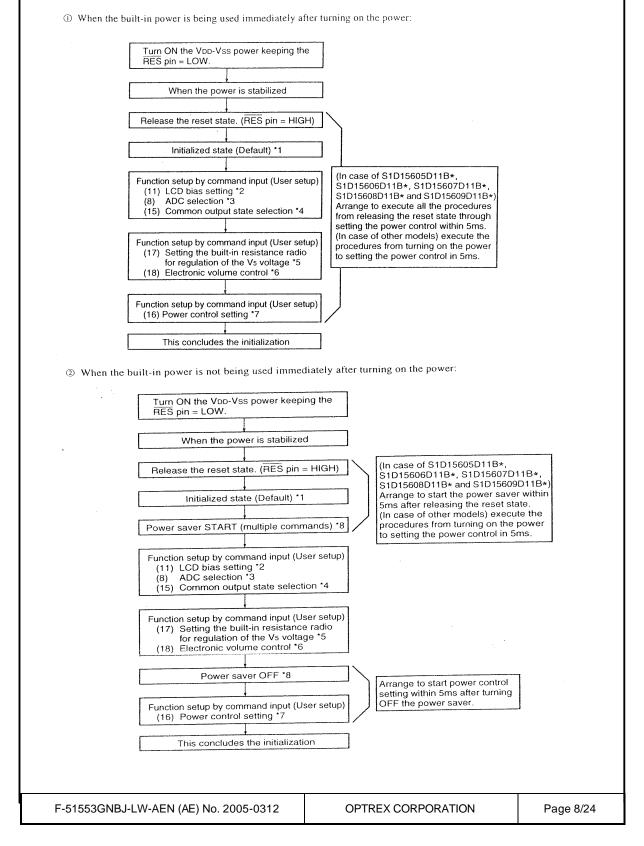


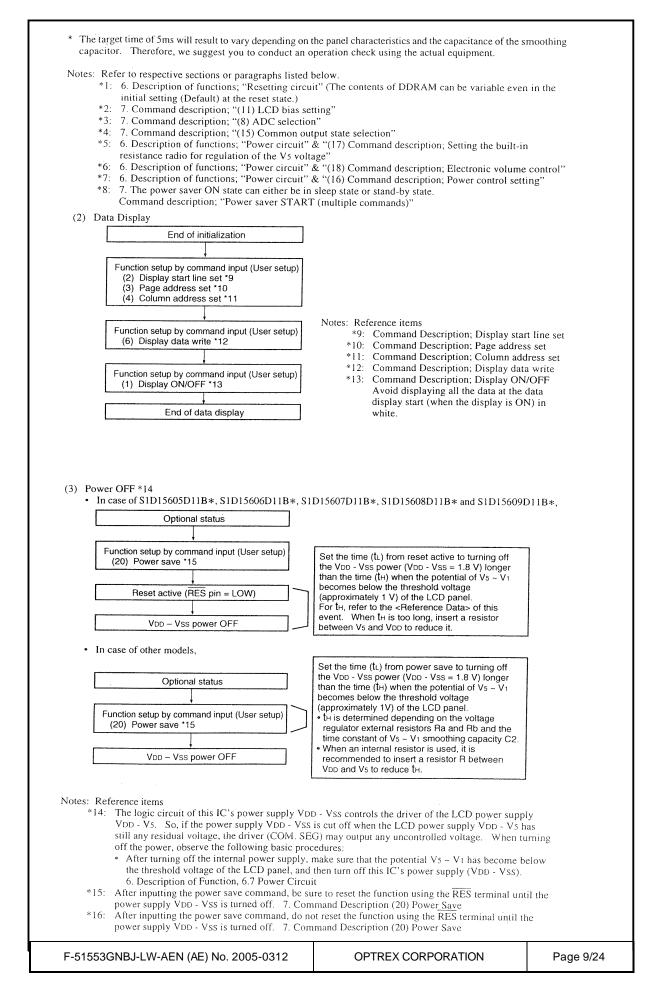
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#### Instruction Setup: Reference (reference)

(1) Initialization

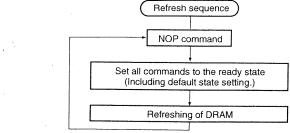
Note: With this IC, when the power is applied, LCD driving non-selective potentials V2 and V3 (SEG pin) and V1 and V4 (COM pin) are output through the LCD driving output pins SEG and COM. When electric charge is remaining in the smoothing capacitor connecting between the LCD driving voltage output pins (V1 ~ V5) and the VDD pin, the picture on the display may become totally dark instantaneously when the power is turned on. To avoid occurrence of such a failure, we recommend the following flow when turning on the power.





#### (4) Refresh

It is recommended that the operating modes and display contents be refreshed periodically to prevent the effect of unexpected noise.



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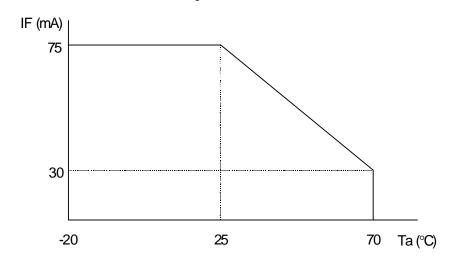
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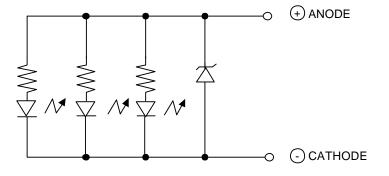
#### 2.4. Lighting Specifications

2.4.1. Absolute Maximum Ratings

	Ų					
					Ta=25°	C (1Unit)
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Foward Current	lF	Note 1	-	-	75	mA
Reverse Voltage	Vr	-	-	-	8	V
LED Power Dissipation	PD	-	-	-	0.375	W

Note 1 : Refer to the foward current derating curve.





#### 2.4.2. Operating Characteristics

							Ta=25°C
Parameter	Symbol	Co	onditions	Min.	Тур.	Max.	Units
Foward Voltage	Vf	IF	=40mA	-	5.0	-	V
Luminance of	L	١F	=40mA	65	100	-	cd/m <sup>2</sup>
Backlight Surface							
Dackinght Sullace		<u> </u>				<u> </u>	
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## 3. Optical Specifications

3.1.LCD Driving Voltage

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Recommended		Ta= -20°C	-	-	9.1	V
LCD Driving Voltage	Vdd-V5	Ta=25°C	7.8	8.5	9.1	V
Note 1		Ta=70°C	7.4	-	-	V

Note 1 : Voltage (Applied actual waveform to LCD Module) for the best contrast. The range of minimum and maximum shows tolerance of the operating voltage. The specified contrast ratio and response time are not guaranteed over the entire range.

**3.2. Optical Characteristics** 

Ta=25°C, 1/65 Duty, 1/7 Bias, Vop=8.5V (Note 4), θ= 0°, φ= - °

Pa	rameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Contrast Ra	atio Note 1	CR	$\theta$ = 0°, $\phi$ = - °	-	8	-	
Viewing Ang	gle			Shown i	n 3.3		
Response	Rise Note 2	Τον	-	-	160	240	ms
Time	Decay Note 3	Toff	-	-	190	290	ms

Note 1 :Contrast ratio is definded as follows. (CR = LON / LOFF)

LON : Luminance of the ON segments

LOFF: Luminance of the OFF segments

Mesuring Spot : 3mm

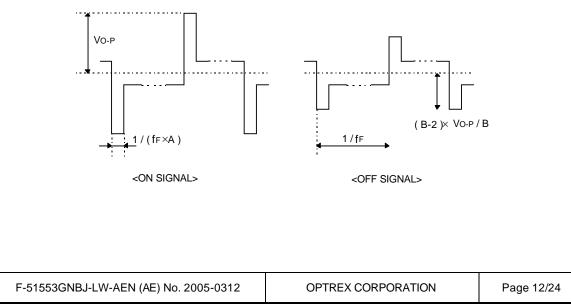
Note 2 :The time that the luminance level reaches 90% of the saturation level from 0% when ON signal is applied.

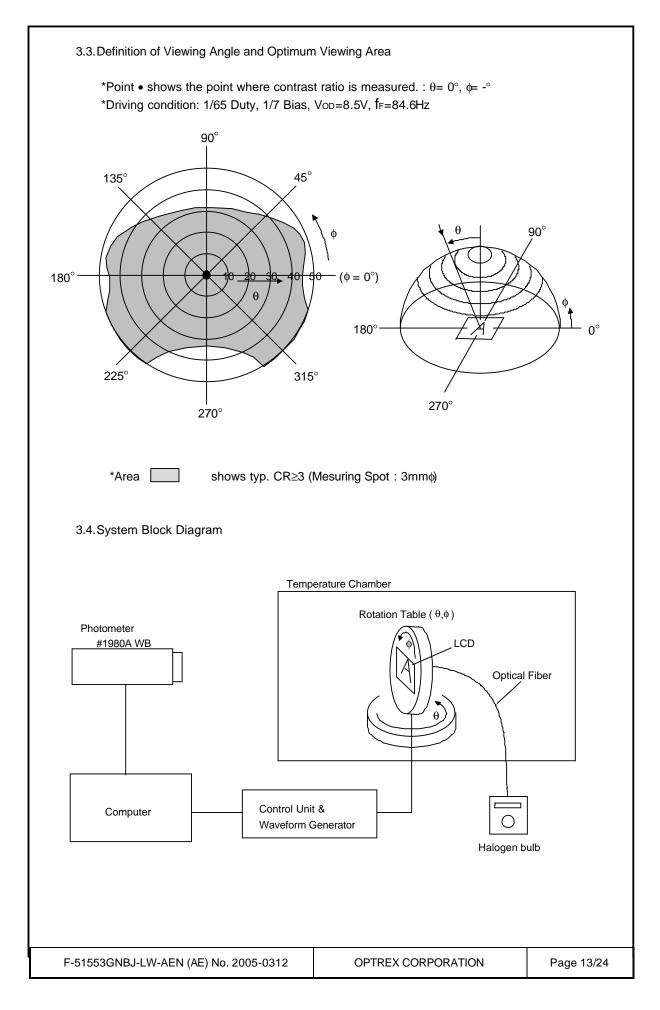
Note 3 :The time that the luminance level reaches 10% of the saturation level from 100% when OFF signal is applied.

Note 4 :Definition of Driving Voltage VoD

Vod=Vcc-Vadj-Vbe

Assuming that the typical driving waveforms shown below are applied to the LCD Panel at 1/A Duty - 1/B Bias (A: Duty Number, B: Bias Number). Driving voltage VoD is definded as the voltage Vo-P when the contrast ratio (CR=LON / LOFF) is at its maximum.

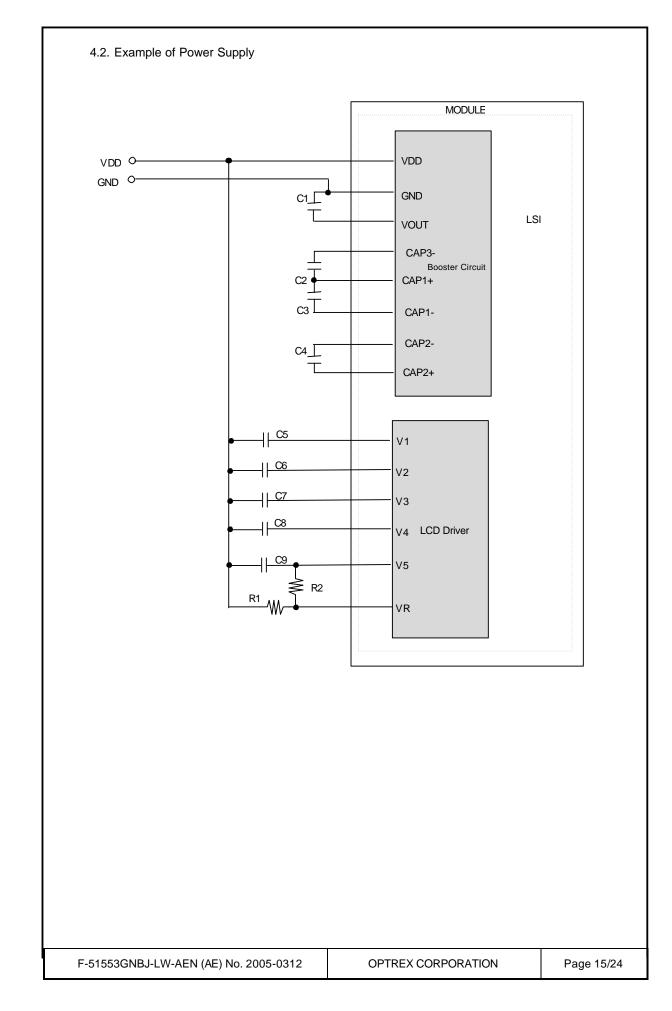


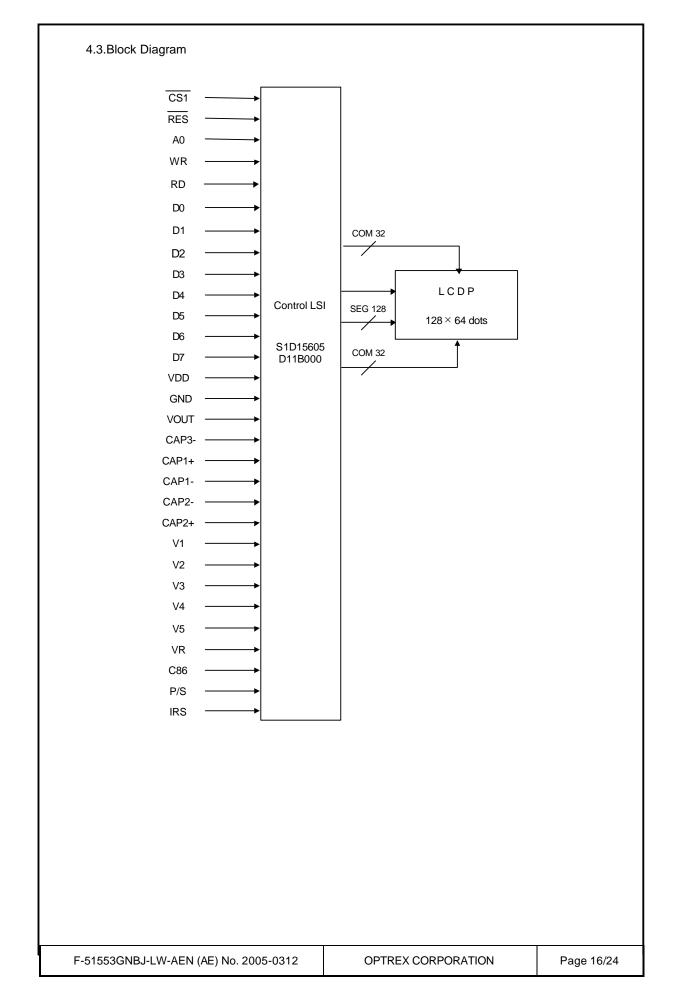


4.I/O Terminal

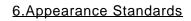
4.1.Pin Assignment

No.	Symbol		Function		
1	CS1	Chip Select Signal L : A	Active		
2	RES	Reset Signal L : Reset			
3	A0	H : D0~D7 are Display I	Data L : D0~D7 are Instructions		
4	WR	Write Signal L : Active			
5	RD	Read Signal L : Active			
6	D0	Data Bus Line			
7	D1	Data Bus Line			
8	D2	Data Bus Line			
9	D3	Data Bus Line			
10	D4	Data Bus Line			
11	D5	Data Bus Line			
12	D6	Data Bus Line			
13	D7	Data Bus Line			
14	Vdd	Power Supply for Logic			
15	GND	Power Supply ( 0V, GN	D )		
16	Vout	DC/DC Voltage Converter Output			
17	CAP3-	DC/DC Voltage Converter Negative Connection			
18	CAP1+	DC/DC Voltage Converter Positive Connection			
19	CAP1-	DC/DC Voltage Converter Negative Connection			
20	CAP2-	DC/DC Voltage Convert	er Negative Connection		
21	CAP2+	DC/DC Voltage Convert	er Positive Connection		
22	V1	Power Supply for LCD E	Drive $V_1 = 1/7, V_5$		
23	V2	Power Supply for LCD E	Drive $V_2 = 2/7, V_5$		
24	V3	Power Supply for LCD D	Drive $V_3 = 5/7, V_5$		
25	V4	Power Supply for LCD D	Drive $V_4 = 6/7, V_5$		
26	V5	Power Supply for LCD E	Drive V5,Vout		
27	VR	Voltage Adjustment Pin			
28	C86	Interface Mode Select S	Signal H : 68 series L : 80 series		
29	P/S	Parallel / Serial Data Se	elect Signal H: Parallel L: Serial		
30	IRS	This terminal selects the	e resistors for the V5 voltage level adju	stment.	
		IRS="H" :Use the intern	al resistors		
		IRS="H" :Do not use the	e internal resistors. The V5 voltage		
		level is requlated by an	external resistive voltage divider attache	ed	
		to the VR terminal.			
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tests will be not conducted under functioning state.         No.       Parameter       Conditions         1       High Temperature Operating       70°C±2°C, 96hrs (operation state)       2         2       Low Temperature Operating       -20°C±2°C, 96hrs (operation state)       3         3       High Temperature Storage       85°C±2°C, 96hrs       4         4       Low Temperature Storage       -30°C±2°C, 96hrs       5         5       Damp Proof Test       40°C±2°C, 90-95%RH, 96hrs       6         6       Temperature Cycle Test       5 Cycle       10°C±2°C, 90-95%RH, 96hrs         6       Temperature Cycle Test       5 Cycle       10°C±2°C, 90-95%RH, 96hrs         7       Shock Test       The function test shall be conducted after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         1       Up of the concrete surface in packing state.       10°C       10°	Conditio	ns: Unless otherwise specified Temperature: 20±5°C Humidity : 65±5%RH	d, tests will be conducted under the following conc	lition.
1       High Temperature Operating       70°C±2°C, 96hrs (operation state)         2       Low Temperature Operating       -20°C±2°C, 96hrs (operation state)         3       High Temperature Storage       85°C±2°C, 96hrs         4       Low Temperature Storage       -30°C±2°C, 96hrs         5       Damp Proof Test       40°C±2°C, 90-95%RH, 96hrs         6       Temperature Cycle Test       5 Cycle         7       Shock Test       The function test shall be conducted after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping Borne 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping Borne 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping Borne 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping Borne 60cm high on the concrete surface in packing aconce Hadded borne dropping Borne 60cm high		-	under functioning state.	
2       Low Temperature Operating       -20°C±2°C, 96hrs (operation state)         3       High Temperature Storage       85°C±2°C, 96hrs         4       Low Temperature Storage       -30°C±2°C, 96hrs         5       Damp Proof Test       40°C±2°C, 90-95%RH, 96hrs         6       Temperature Cycle Test       5 Cycle         7       Shock Test       The function test shall be conducted after 4 hours storage at the normal temperature concerned surface         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         0       Image: Concerned surface       Fig.6 lace : once         0       The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.	No.	Parameter	Conditions	Notes
3       High Temperature Storage       85°C±2°C, 96hrs         4       Low Temperature Storage       -30°C±2°C, 96hrs         5       Damp Proof Test       40°C±2°C,90–95%RH,96hrs         6       Temperature Cycle Test       5 Cycle         7       Shock Test       The function test shall be conducted after 4 hours storage at the normal temperature dopping BCD period         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         0       Image: Storage at the normal temperature dopping BCD period comer dropping BCD period buffer to be beserved.         Note 1 :No dew condensation to be observed.       Note 2 :The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after removed from the test chamber.	1	High Temperature Operating	70°C±2°C, 96hrs (operation state)	
4       Low Temperature Storage       -30°C±2°C, 96hrs         5       Damp Proof Test       40°C±2°C,90-95%RH, 96hrs         6       Temperature Cycle Test       5 Cycle         7       Shock Test       The function test shall be conducted after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         0       Image: Surface of the surface of	2	Low Temperature Operating	-20°C±2°C, 96hrs (operation state)	1
5       Damp Proof Test       40°C±2°C,90~95%RH, 96hrs         6       Temperature Cycle Test       5 Cycle       1 Cycle         7       Shock Test       The function test shall be conducted after dropping from 60cm high on the concrete surface in packing state.       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         7       Shock Test       To be measured after dropping BC.Dedge : once Face	3	High Temperature Storage	85°C±2°C, 96hrs	2
<ul> <li>6 Temperature Cycle Test</li> <li>6 Cycle</li> <li>7 Shock Test</li> <li>8 Score dropping from 60cm high on the concrete surface in packing state.</li> <li>9 Score dropping B, Score</li></ul>	4	Low Temperature Storage	-30°C±2°C, 96hrs	1,2
Image: Second state of the second s	5	Damp Proof Test	40°C±2°C,90~95%RH, 96hrs	1,2
7       Shock Test       To be measured after dropping from 60cm high on the concrete surface in packing state.         Image: state of the concrete surface in packing state.       Image: state of the concrete surface in packing state.         Image: state of the concrete surface in packing state.       Image: state of the concrete surface in packing state.         Image: state of the concrete surface in packing state.       Image: state of the concrete surface in packing state.         Image: state of the concrete surface in packing state.       Image: state of the concrete state of the concrete state of the concrete state of the concrete surface in packing state.         Image: state of the state of the concrete state o			The function test shall be conducted arter 1 hours storage at the normal temperature and	
Note 2 :The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after removed from the test chamber.	7	Shock Test	the concrete surface in packing state. Dropping method corner dropping A corner : once Edge dropping B,C,D edge : once Face dropping E,F,G face : once	n
	Note 2 :	The function test shall be conduc Temperature and humidity after re	ted after 4 hours storage at the normal emoved from the test chamber.	

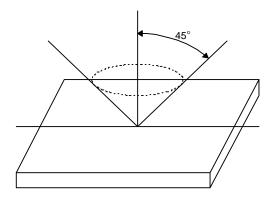


6.1. Inspection conditions

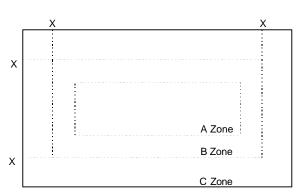
The LCD shall be inspected under 40W white fluorescent light.

The distance between the eyes and the sample shall be more than 30cm.

All directions for inspecting the sample should be within 45° against perpendicular line.



6.2. Definition of applicable Zones



X : Maximum Seal Line

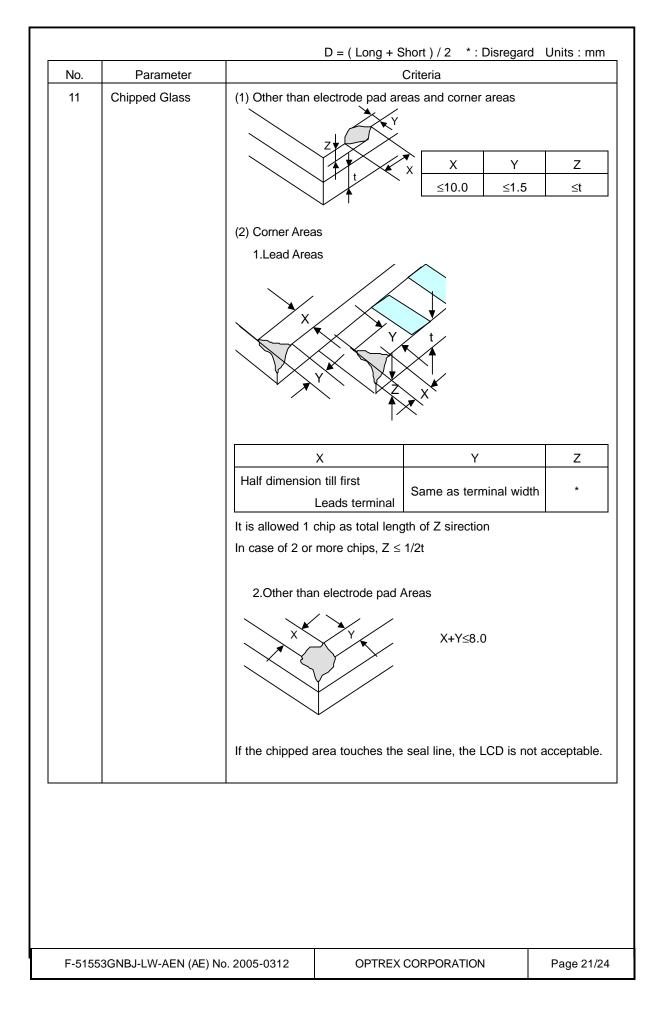
A Zone : Active display area

B Zone : Out of active display area ~ Maximum seal line C Zone : Rest parts

A Zone + B Zone = Validity viewing area

No.	Parameter			Crite	ria	
1	The Shape of Dot	(1) Pin Hole		2.110		
			Dimensio	n	Acceptable	Number
			D ≤ 0		*	
					1 pc / dot(only se	eament)or les
			0.10 < D ≤ 0.	20	5 pcs / cell or les	
		(2) Pattern Sh	ift			
		A B	A – B	≤ 0.15	5	
			←			
		(3) Breakage o	or Chips / Defor	mation	I	
		А	1.Segment Typ	be		
			Dimensio	n	Acceptable	Number
			A ≤ 0.10	)	*	
			B ≤ 0.15	;	*	
		B	2.Dot Type			
			Dimension		Acceptable Nu	mber
		A →    ←	A≤0.10		*	
				(Shou	Ild not be connecte	ed to next dot
				1 pc /	dot(only segment	)or less
		Ğ → B ←	0.10 <a≤0.15< td=""><td>5 pcs</td><td>/ cell or less</td><td></td></a≤0.15<>	5 pcs	/ cell or less	
				(Shou	Ild not be connecte	ed to next dot
			B ≤ 0.15		*	
		3.[	Defective type e	extends	s over multiple num	bers of dots
			Dimension		Acceptable Nu	mber
			D≤0.10		*	
		<b>┲</b> ╋┲		1 pc /	dot(only segment	)or less
		'→   ←	0.40 0.000	5 pcs	/ cell or less	
			0.10 <d≤0.20< td=""><td>(Individ</td><td>dual dot must secu</td><td>ıre 1/2 area</td></d≤0.20<>	(Individ	dual dot must secu	ıre 1/2 area
				or me	ore)	

2 3 4	Black and White Spots, Foreign Substances	0.20< Individual do	Zone $D \le 0.10$ $D \le 0.20$ $D \le 0.30$ ot must secure 1/2	A * 6 4 area or more Acce A * 5 4	eptable Nur B * 6 4	C *
		$0.10 < 0.20 <$ Individual do $(2) \text{ Line Shape}$ $Length$ $*$ $L \leq 2.0$ $L \leq 1.0$ $*$	D ≤ 0.10 D ≤ 0.20 D ≤ 0.30 th must secure 1/2 Zone Width $W \le 0.03$ 0.03 <w 0.05<br="" ≤="">≤ 0.10</w>	A * 6 4 area or more Acce A * 5 4	B * 6 4	C           *           *           *           mber           C           *
	Foreign Substances	$0.10 < 0.20 <$ Individual do $(2) \text{ Line Shape}$ $Length$ $*$ $L \leq 2.0$ $L \leq 1.0$ $*$	D ≤ 0.20 D ≤ 0.30 th must secure 1/2 S Width W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	* 6 4 area or more Acce A * 5 4	* 6 4	* * * * mber C *
		0.20 < Individual do (2) Line Shape Length * L < 2.0 L < 1.0 *	D ≤ 0.20 D ≤ 0.30 th must secure 1/2 S Width W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	6 4 area or more Acce A * 5 4	6 4 ptable Nu B * 5	mber C *
		0.20 < Individual do (2) Line Shape Length * L < 2.0 L < 1.0 *	D ≤ 0.30 t must secure 1/2 Zone Width $W \le 0.03$ 0.03 <w 0.05<br="" ≤="">≤ 0.10</w>	4 area or more Acce A * 5 4	4	mber C *
		Individual do (2) Line Shape Length * $L \leq 2.0$ $L \leq 1.0$ *	t must secure 1/2 Zone Width W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	Acce A * 5 4	ptable Nu B * 5	mber C *
		(2) Line Shape Length ★ L ≤2.0 L ≤1.0 ★	e Zone Width W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	Acce A * 5 4	ptable Nur B * 5	C *
		Length	Zone Width ₩≤0.03 0.03<₩≤0.05 ≤0.10	A * 5 4	B * 5	C *
		* L ≤2.0 L ≤1.0	W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	A * 5 4	B * 5	C *
		* L ≤2.0 L ≤1.0	W≤0.03 0.03 <w≤0.05 ≤0.10</w≤0.05 	* 5 4	5	*
		L ≤1.0 *	0.03 <w≤0.05 ≤0.10</w≤0.05 	4		*
		L ≤1.0 *	≤0.10	4		
			0.10 <w< td=""><td></td><td></td><td>*</td></w<>			*
		No more that		In the sam	e way (1)	*
4	Color Variation Air Bubbles	Not to be con	spicuous defects.			
-	(between glass		Zone	Acce	ptable Nu	mber
	& polarizer)	Dimension		A	B	С
			D ≤ 0.30	*	*	*
		0.30<	D ≤ 0.40	3	*	*
			D ≤ 0.60	2	3	*
		No more that (Refer to "Co	ects")			
5	Polarizer Scratches	Not to be conspicuous defects.				
6	Polarizer Dirts	If the stains are removed easily from LCDP surface, the module is not defective.				
7	Complex Foreign Substance Defects	Black spots, line shaped foreign substances or air bubbles between				
8	Distance between Different Foreign Substance Defects	glass & polarizer should be 9pcs maximum in total. 20mm or more				



7.Code System of Production Lot		
The production lot of module is specifie	ed as follows.	
Factory Code Factory Code Production Week Production Month (1~9, 2 Production Year (Lower 2 digits	(1~5) X, Y, Z)	9)
8.Type Number		
The type number of module is specified	as follows.	
F-51553GNBJ-LW-AEN		
Please contact us when questions and Specifications arise.	/or new problems not specified in this	
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### 10.Precautions Relating Product Handling

The Following precautions will guide you in handling our product correctly.

- 1) Liquid crystal display devices
- 1. The liquid crystal display device panel used in the liquid crystal display module is made of plate glass. Avoid any strong mechanical shock. Should the glass break handle it with care.
- 2. The polarizer adhering to the surface of the LCD is made of a soft material. Guard against scratching it.
- 2) Care of the liquid crystal display module against static electricity discharge.
- 1. When working with the module, be sure to ground your body and any electrical equipment you may be using. We strongly recommend the use of anti static mats (made of rubber), to protect work tables against the hazards of electrical shock.
- 2. Avoid the use of work clothing made of synthetic fibers. We recommend cotton clothing or other conductivity-treated fibers.
- 3. Slowly and carefully remove the protective film from the LCD module, since this operation can generate static electricity.
- 3) When the LCD module alone must be stored for long periods of time:
- 1. Protect the modules from high temperature and humidity.
- 2. Keep the modules out of direct sunlight or direct exposure to ultraviolet rays.
- 3. Protect the modules from excessive external forces.
- 4) Use the module with a power supply that is equipped with an overcurrent protector circuit, since the module is not provided with this protective feature.
- 5) Do not ingest the LCD fluid itself should it leak out of a damaged LCD module. Should hands or clothing come in contact with LCD fluid, wash immediately with soap.
- 6) Conductivity is not guaranteed for models that use metal holders where solder connections between the metal holder and the PCB are not used. Please contact us to discuss appropriate ways to assure conductivity.
- 7) For models which use CFL:
- 1. High voltage of 1000V or greater is applied to the CFL cable connector area. Care should be taken not to touch connection areas to avoid burns.
- 2. Protect CFL cables from rubbing against the unit and thus causing the wire jacket to become worn.
- 3. The use of CFLs for extended periods of time at low temperatures will significantly shorten their service life.
- 8) For models which use touch panels:
  - 1. Do not stack up modules since they can be damaged by components on neighboring modules.
- 2. Do not place heavy objects on top of the product. This could cause glass breakage.
- 9) For models which use COG, TAB, or COF:
- 1. The mechanical strength of the product is low since the IC chip faces out unprotected from the rear. Be sure to protect the rear of the IC chip from external forces.
- 2. Given the fact that the rear of the IC chip is left exposed, in order to protect the unit from electrical damage, avoid installation configurations in which the rear of the IC chip runs the risk of making any electrical contact.

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- 10) Models which use flexible cable, heat seal, or TAB:
- 1. In order to maintain reliability, do not touch or hold by the connector area.
- 2. Avoid any bending, pulling, or other excessive force, which can result in broken connections.
- 11) In case of buffer material such as cushion / gasket is assembled into LCD module, it may have an adverse effect on connecting parts (LCD panel-TCP / HEAT SEAL / FPC / etc., PCB-TCP / HEAT SEAL / FPC etc., TCP-HEAT SEAL, TCP-FPC, HEAT SEAL-FPC, etc.,) depending on its materials.

Please check and evaluate these materials carefully before use.

12) In case of acrylic plate is attached to front side of LCD panel, cloudiness (very small cracks) can occur on acrylic plate, being influenced by some components generated from polarizer film..

Please check and evaluate those acrylic materials carefully before use.

#### 11.Warranty

This product has been manufactured to your company's specifications as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in medical devices, nuclear power control equipment, aerospace equipment, fire and security systems, or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. If the product is to be used in any of the above applications, we will need to enter into a separate product liability agreement.

- 1. We cannot accept responsibility for any defect, which may arise from additional manufacturing of the product (including disassembly and reassembly), after product delivery.
- 2. We cannot accept responsibility for any defect, which may arise after the application of strong external force to the product.
- 3. We cannot accept responsibility for any defect, which may arise due to the application of static electricity after the product has passed your company's acceptance inspection procedures.
- 4. When the product is in CFL models, CFL service life and brightness will vary According to the performance of the inverter used, leaks, etc. We cannot accept responsibility for product performance, reliability, or defect, which may arise.
- 5. We cannot accept responsibility for intellectual property of a third party, which may arise through the application of our product to your assembly with exception to those issues relating directly to the structure or method of manufacturing of our product.
- 6. Optrex will not be held responsible for any quality guarantee issue for defect products judged as Optrex-origin longer than 2 (two) years from Optrex production or 1(one) year from Optrex, Optrex America, Optrex Europe delivery which ever comes later.

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